

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

OFFICE TO	EXAMINER:	N. PAREKH)	
3	APPLICANT:	PETER ELENIUS, ET AL.) Art Unit 2811	
4	SERIAL NO.:	09/575,298)	
5	FILED:	May 19, 2000)	
6		R BAR FOR HIGH POWER	}	
7	FLIP CH	IPS"		
8	т.			
9	Sta	nereby certify that this correspond ates Postal Service as first class managed.	ail in an envelope addressed	to:
10	Commissioner for Patents, Washington, D.C. 20231 on: January 28, 2002 Marvin A. Glazer			
11	Na A	me of Registered Rep.		
12	Signature Day 28, 2002 Date			
13		<i>y</i>		
14				
15		AMEND	<u>MENT</u>	TECH
16	Honorable Commissioner for Patents Washington, D.C. 20231			REC FEB
17	Sir:			RECEIVED FEB 19 2003 FECHNOLOGY CENTER
		IN THE CLAIMS:		m =
18		<u>IS:</u>		YTE NEED
18 19	IN THE CLAIM	IS: end claim 16 as follows:		/ED 2003 HTER 280
	IN THE CLAIM Please am		formed upon an upper sur	2800
19 20	IN THE CLAIM Please am 16. (Amer	end claim 16 as follows: nded) A <u>reflowable</u> solder bar		Secondariant face of a first
19 20 21	IN THE CLAIM Please am 16. (Amenous substrate, the first	end claim 16 as follows:	al contact, said reflowable	face of a first solder bar being
19 20 21 22	IN THE CLAIM Please am 16. (Amer substrate, the first adapted to join the	end claim 16 as follows: nded) A <u>reflowable</u> solder bar t substrate having a first electric	al contact, said <u>reflowable</u> ond electrical contact on a	face of a first solder bar being
19 20 21 22	IN THE CLAIM Please am 16. (Amer substrate, the first adapted to join the said reflowable so	end claim 16 as follows: nded) A <u>reflowable</u> solder bar t substrate having a first electric e first electrical contact to a sec	al contact, said reflowable ond electrical contact on a ation:	face of a first solder bar being second substrate
19 20 21 22 23 24	Please am 16. (Amer substrate, the first adapted to join the said reflowable so a. a first g	end claim 16 as follows: nded) A reflowable solder bar t substrate having a first electric e first electrical contact to a seconder bar comprising in combina	al contact, said reflowable ond electrical contact on a ation: med upon the upper surfac	face of a first solder bar being second substrate e of the first
19 20 21 22 23 24 25	Please am 16. (Amer substrate, the first adapted to join the said reflowable so a. a first g	end claim 16 as follows: nded) A reflowable solder bar t substrate having a first electric e first electrical contact to a sec older bar comprising in combinate enerally circular solder pad form	al contact, said reflowable ond electrical contact on a ation: med upon the upper surfac	face of a first solder bar being second substrate e of the first

28 substrate, the second generally circular solder pad having a center, and having said first